

Subject: Invitation to attend the 3rd BMEMat–Advanced Materials Joint Symposium in Hong Kong

Dear Professor Fang Tang,

As a conference chair, it is my great pleasure to invite you to attend the **3rd BMEMat–Advanced Materials Joint Symposium** and give an oral presentation at the Chinese University of Hong Kong. The symposium is hosted by the Chinese University of Hong Kong in conjunction with *BMEMat* and *Advanced Materials*.

The symposium will be held in person with the following details:

- **Dates:** November 6–9, 2026
- **Venue:** Cheng Yu Tung Building
- **Address:** The Chinese University of Hong Kong, 12 Chak Cheung Street, Sha Tin, New Territories, Hong Kong, China

The symposium will bring together leading scientists, journal editors, clinicians, industry representatives, and early-career researchers from Hong Kong, Mainland China, and overseas. The scientific program will cover emerging topics in biomaterials and biomedical engineering, including drug delivery and theranostics, smart and responsive biomaterials, cancer diagnostics and therapy, regenerative medicine, bioelectronics, biosensing and bioimaging, AI-driven biomaterial design, antimicrobial materials and vaccines, phage therapy, and synthetic biology.

The symposium will also feature the following highlights:

- **Internationalization:** Dedicated sessions for international participants and specific countries
- **Editor Panel:** Live discussions with leading editors from *Advanced Materials* and the *Nature* portfolio
- **Funding Insights:** NSFC application strategies, including Hong Kong–Mainland Joint Schemes
- **New Opportunities:** Introduction to the New Cornerstone Investigator Program
- **Academic Foresight:** Perspectives from distinguished experts in China and overseas

Your participation would greatly enhance the scientific impact and success of the symposium, and we look forward to welcoming you and benefiting from your expertise.

We hope to see you in Hong Kong!

Sincerely,



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邀请函

主题：邀请参加第三届 BMEMat-Advanced Materials 香港联合学术研讨会

尊敬的汤芳教授：

作为本次会议主席，我谨诚挚邀请您赴香港中文大学参加**第三届 BMEMat-Advanced Materials 联合学术研讨会**，并作口头报告。本次研讨会由香港中文大学联合 BMEMat 期刊与《先进材料》(Advanced Materials) 期刊共同主办。

本次研讨会为线下会议，具体信息如下：

会议时间：2026 年 11 月 6 日-9 日

会议地点：郑裕彤楼

会议地址：中国香港新界沙田泽祥街 12 号，香港中文大学

本次研讨会汇聚来自中国内地、香港及海外的顶尖科学家、期刊编辑、临床医师、产业界代表以及青年科研人员。会议学术议程聚焦生物材料与生物医学工程前沿方向，涵盖药物递送与诊疗一体化、智能响应型生物材料、癌症诊断与治疗、再生医学、生物电子学、生物传感与生物成像、人工智能驱动的生物材料设计、抗菌材料与疫苗、噬菌体疗法以及合成生物学等议题。

本次研讨会设有多项特色环节：

1. 国际交流专场：专为境外参会学者设置分论坛，面向不同国家学者开展交流
2. 编辑圆桌论坛：与《先进材料》以及自然系列期刊的资深编辑开展现场交流研讨
3. 基金申报经验分享：国家自然科学基金申报策略解读，包括内地-香港联合项目专项
4. 科研机遇介绍：新基石研究员项目宣讲
5. 学术前沿展望：海内外知名专家分享学科发展见解

您的参与将极大提升本次研讨会的学术影响力，助力会议取得圆满成功。我们期待您的到来，也期待聆听您的学术见解。

期待与您相聚香港！

此致 敬礼

毛传斌 全球 STEM 讲席教授

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